Product specification

Product:	Silver and palladium paste
Part number:	02H-1805

Application scope :
This product is suitable for thick film circuit and sensor.

Usage conditions:

Substrate	Alumina ceramic
Printing	200-300 mesh screen printing
Leveling	Let it level at room temperature for 5-15 minutes (depending on the actual leveling situation).
Drying &Sintering	Bake in an oven at 100-150°C for 10-15 minutes Sintering in a tunnel furnace under air atmosphere at a peak temperature of 850°C (recommended) for 10 minutes.
Thinner	ST-1000

Characteristics:

1. Paste characteristics:

Characteristic		Standard	Test method and conditions
1	Fineness	≤5μm	FOG test
2	Viscosity	130-280Pa.s	Rookefield HBT (Boli Fei) viscometer, rotor model SC4-14/6R, operating at 10 rpm, with viscosity adjustable within 25±1°C according to user requirements.

2. Characteristics after curing:

Under sintering conditions 1, the film thickness ranges from 8 to 12 microns Check fired film produced under the conditions specified in 1）, (Film thickness is 8-12μm.)

Characteristics		Standard	Test method and conditions
3	Resistivity 方阻	≤10mΩ/□	Test pattern 0.6mm×60mm
4	Adhesion		Peel Test: 0.5mmφ Tin plated Cu wire soldered on 2mm×2mm Pad. Solder: 96.5Sn/0.5Cu Mildly activated flux used.
	Initial	≥46.5N	

Save conditions and validity period :

The product should be stored in a sealed environment at 5-25°C. The shelf life is 1 year from the date of shipment.

Packaging method：

Standard packaging: 1000g per can. Samples are available in 200g small cans.